IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	Material Compo © Copyright 2005. IP international and Pan-	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and M	fg Informati	ion		
upplier Infor									,					
Company name*			Company unique ID			τ	Unique ID Authority				Response Date*			
nsemi											2024-05-17			
Contact Name		Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-Env-Stev	wards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			1	Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Reques	Requester Item Number Mfr		tem Number Mfr Item Name				Effective Date	Version	n I	Manufacturing Site		Weight*	UOM	Unit Type
		NRVS2N	S2M SR SMB GPPN 1.5A 1000V		5A 1000V		2024-05-17		,	TSCBE		90.0004	mg	Each
Ianufacturing	g Proccess Informati	ion												
Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-020 MS		SL Rating	Peak Process Body Tempera		Temperatu	ture Max Time at Peak Tempera		ure Numb	er of Reflow Cyc	les		
Matte Tin (Sn) - annealed		CU Alloy 1			260 C 3		30	secon	ds 3					
omments														
vel 1 - maximum	ı time at peak temperatuı	re during sol	dering is 10-3	30 seconds										
or more informa	tion regarding material c	composition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itability and the Company's remedies for issues that arise regarding information the Supplier provides in this fo										
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature R		,								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	10.667	mg	Supplier	Copper (Cu)	7440-50-8		10.667	mg
Die	1.2132	mg	Supplier	Silicon (Si)	7440-21-3		1.0919	mg
			В	Nickel (Ni)	7440-02-0		0.0079	mg
			Supplier	Gold (Au)	7440-57-5		0.0018	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.1116	mg
Die Attach Solder	2.3616	mg	Supplier	Silver (Ag)	7440-22-4		0.059	mg
			A	Lead (Pb)	7439-92-1	7a	2.1845	mg
			Supplier	Tin (Sn)	7440-31-5		0.1181	mg
Lead Frame	26.802	mg	Supplier	Iron (Fe)	7439-89-6		0.0322	mg
			Supplier	Copper (Cu)	7440-50-8		26.7618	mg
			Supplier	Phosphorus (P)	7723-14-0		0.008	mg
Mold Compound-Black	48.755	mg		Metal Hydroxide	proprietary data		1.7064	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		3.9004	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2438	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		39.004	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.9004	mg
Plating	0.2016	mg	Supplier	Tin (Sn)	7440-31-5		0.2016	mg